AMENDMENT AND RESPONSE UNDER 37 CFR § 1.111

Serial Number: 10/807,220 Filing Date: March 22, 2004

Title: HEAT SPREADER WITH DOWN SET LEG ATTACHMENT FEATURE

Assignee: Intel Corporation

IN THE CLAIMS

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Please amend the claims as follows:

Claims 1-6. (Canceled)

7. (Currently Amended) A method of forming a heat spreader comprising:

forming a mass of material <u>into a body</u> approximately rectangular in shape <u>having a top</u> <u>surface</u>, a bottom surface and at least one corner; and

forming at least three [[one]] downset <u>legs</u> [[leg]] on the mass of material, wherein the at least three downset legs are formed to be downset from the bottom surface and wherein the at least three downset legs and the bottom surface define a cavity.

- 8. (Currently Amended) The method of claim 7, wherein the forming <u>a mass of material</u> comprises at least one cold forming process.
- 9. (Currently Amended) The method of claim 7, wherein the method further comprises forming at least one <u>notch</u> corner on the mass of material, wherein the <u>notch</u> at least one downset leg is formed in the vicinity of the corner.
- 10. (Original) The method of claim 7, wherein at least one void is formed on the at least one downset leg, wherein the void is configured to receive at least one mechanical attachment device.
- 11. (Currently Amended) The method of claim 7, wherein the at least one downset leg is formed to be configured to receive received at least one clamp.

12-25. (Canceled)

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26. (New) The method of claim 7, wherein the at least one downset leg is formed to be

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configured to received at least one clip.

27. (New) The method of claim 7, further comprising forming at least one notch formed

between the top surface and the bottom surface proximate to the at least one corner.

28. (New) A method of forming a heat spreader comprising:

forming a body having a top surface, a bottom surface, at least one side and at least one

corner;

forming at least three downset legs formed to be downset from the body bottom surface

by a distance wherein the at least three downset legs and the body bottom surface define a cavity

between the legs.

29. (New) The method of claim 28 wherein forming the body includes forming the body

with four downset legs formed thereon, and wherein each downset leg is formed proximate to a

separate corner of the heat spreader body.

30. (New) The method of claim 28, wherein forming the at least one downset legs further

includes forming the downset legs with a void formed therein, and wherein the void is

configured to receive at least one mechanical attachment device.

31. (New) The method of claim 28, further including forming at least one downset leg to be

configured to receive at least one clip.

32. (New) The method of claim 28, wherein the body and at least one downset leg are

comprised of thermally conductive material.

33. (New) The method of claim 28, wherein the cavity is configured to receive at least one

microelectronic die.

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34. (New) The method of claim 28 wherein forming the body includes forming the body in a rectangular shape.

- 35. (New) The method of claim 28 wherein forming the body includes forming the body in an octagon shape.
- 36. (New) A method of forming a heat spreader, comprising:

forming a body having a top surface, a bottom surface, a periphery and at least one side in a shape having a plurality of corners;

forming a plurality of legs extending down from the bottom surface on the periphery of the body and thereby forming a semiconductor die cavity under the bottom surface of the body, the plurality of legs being attached to a non-contiguous lip around the body; and

forming a notch between the top surface and the bottom surface in proximity to the at least one corner.

- 37. (New) The method of claim 36 further including attaching a microelectronic die to the bottom surface of the bottom surface within the cavity.
- 38. (New) The method of claim 36 wherein forming a plurality of legs includes forming each of the plurality of legs in a corresponding one of the plurality of corners.
- 39. (New) The method of claim 38 further including forming a mechanical attachment mechanism in each of the plurality of corners.
- 40. (New) The method of claim 39 further including forming a notch in the top surface of the body in each of the plurality of corners.
- 41. (New) The method of claim 40 wherein the top surface is approximately rectangular in shape.